



FEATURES

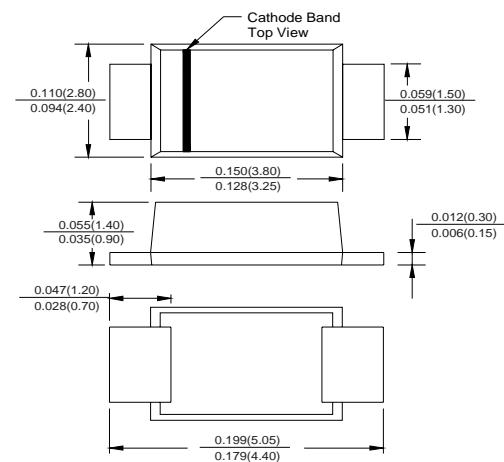
- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- Fast reverse recovery time
- Lead free in comply with EU RoHS 2011/65/EU directives

MECHANICAL DATA

- Case: SMAF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 27mg 0.00086oz



SMAF



Dimensions in inches and (millimeters)

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	RS2AF	RS2BF	RS2DF	RS2GF	RS2JF	RS2KF	RS2MF	Units			
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V			
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V			
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V			
Maximum Average Forward Rectified Current at Ta = 65 °C	I _{F(AV)}	2							A			
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I _{FSM}	50							A			
Maximum Instantaneous Forward Voltage at 2 A	V _F	1.3							V			
Maximum DC Reverse Current Ta = 25 °C at Rated DC Blocking Voltage Ta = 125 °C	I _R	5 100							µA			
Maximum Reverse Recovery Time ¹⁾	t _{rr}	150			250	500			ns			
Typical Junction Capacitance ²⁾	C _j	40							pF			
Typical Thermal Resistance ³⁾	R _{θJA}	65							°C/W			
Operating and Storage Temperature Range	T _j , T _{stg}	-55 ~ +150							°C			

1) Measured with I_F = 0.5 A, I_R = 1 A, I_{rr} = 0.25 A

2) Measured at 1MHz and applied reverse voltage of 4V D.C

3) P.C.B. mounted with 0.5 X 0.5" (12.7 X 12.7 mm) copper pad areas.



Fig.1 Forward Current Derating Curve

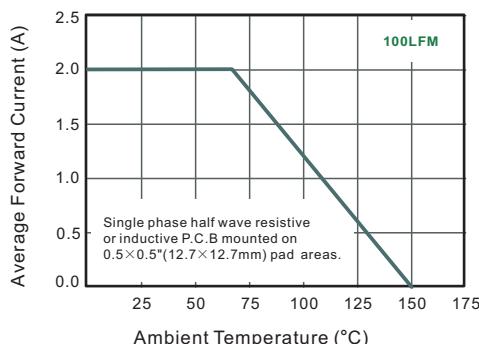


Fig.2 Typical Reverse Characteristics

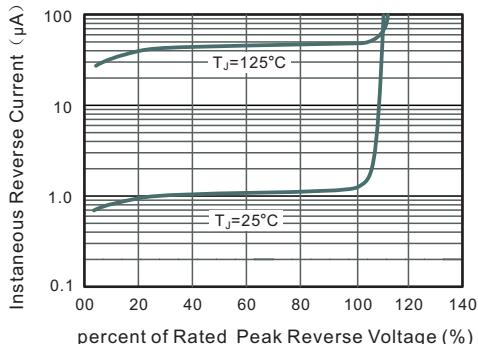


Fig.3 Typical Instantaneous Forward Characteristics

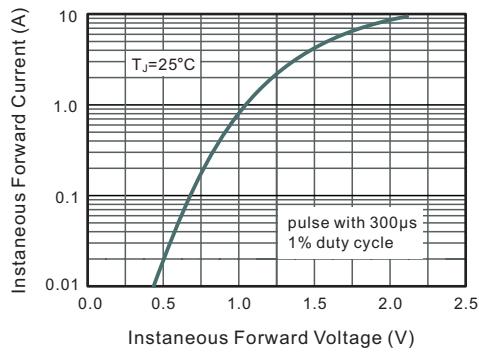


Fig.4 Typical Junction Capacitance

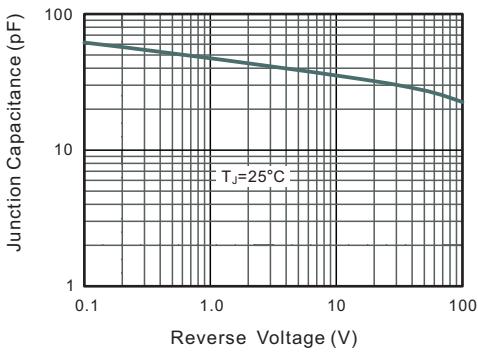


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

